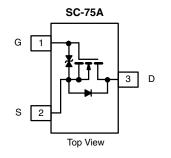


Vishay Siliconix

N-Channel 20 V (D-S) MOSFET

PRODUCT SUMMARY					
V _{DS} (V)	R _{DS(on)} (Ω)	I _D (mA)	Q _g (Typ.)		
20	0.396 at V _{GS} = 4.5 V	600			
	0.456 at V _{GS} = 2.5 V	500	0.75		
	0.546 at V _{GS} = 1.8 V	350	0.75		
	1.100 at V _{GS} = 1.5 V	50			



FEATURES

- TrenchFET[®] Power MOSFET: 1.2 V Rated .
- 100 % Rg Tested
- Gate-Source ESD Protected: 1000 V ٠
- Material categorization: • For definitions of compliance please see www.vishay.com/doc?99912

APPLICATIONS

- Load/Power Switching for Portable Devices
- Drivers: Relays, Solenoids, Lamps, Hammers, Displays, . Memories
- **Battery Operated Systems**
- Power Supply Converter Circuits •

Marking Code: K

Ordering Information:

Si1012CR-T1-GE3 (Lead (Pb)-free and Halogen-free)

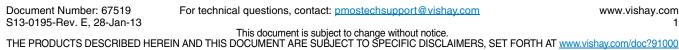
ABSOLUTE MAXIMUM RATINGS ($T_A = 25 \degree C$, unless otherwise noted)					
Parameter		Symbol	Limit	Unit	
Drain-Source Voltage		V _{DS}	20	v	
Gate-Source Voltage		V _{GS}	± 8	- V	
Continuous Drain Current /T 150 °C)ª	T _A = 25 °C	- I _D	0.63 ^{a, b}		
Continuous Drain Current (T _J = 150 °C) ^a	T _A = 70 °C		0.5 ^{a, b}	A	
Pulsed Drain Current (t = 300 µs)		I _{DM}	2		
Continuous Source-Drain Diode Current	T _A = 25 °C	۱ _S	0.2 ^{a, b}	A	
	T _A = 25 °C	Р	0.24 ^{a, b}	w	
Maximum Power Dissipation ^a	T _A = 70 °C	P _D	0.15 ^{a, b}	vv	
Operating Junction and Storage Temperature Ra	T _J , T _{stg}	- 55 to 150	°C		

THERMAL RESISTANCE RATINGS						
Parameter	Symbol	Typical	Maximum	Unit		
	t ≤ 5 s	R _{thJA}	440	530	°C/W	
Maximum Junction-to-Ambient ^D	Steady State		540	650	0/10	

Notes:

a. Surface mounted on 1" x 1" FR4 board.

b. t = 5 s.





COMPLIANT

HALOGEN

FREE

Si1012CR

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Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 V, I_D = 250 \mu A$	20			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	l _D = 250 μA		17		mV/°C	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I _D = 250 μA		- 1.8		mv/°C	
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \ \mu A$	0.4		1	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 8 V$			± 30		
		$V_{DS} = 0 V, V_{GS} = \pm 4.5 V$			± 1		
Zous Oata Maltaga Dusia Ouwant	I _{DSS}	$V_{DS} = 20 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$			1	μΑ	
Zero Gate Voltage Drain Current		$V_{DS} = 20 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 85 ^{\circ}\text{C}$			10		
On-State Drain Current ^a	I _{D(on)}	V_{DS} = \geq 5 V, V_{GS} = 4.5 V	2			Α	
		$V_{GS} = 4.5 \text{ V}, \text{ I}_{D} = 0.6 \text{ A}$		0.330	0.396	Ω	
	Para	$V_{GS} = 2.5 \text{ V}, \text{ I}_{D} = 0.3 \text{ A}$		0.380	0.456		
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = 1.8 V, I _D = 0.3 A		0.420	0.546		
		$V_{GS} = 1.5 \text{ V}, \text{ I}_{D} = 0.05 \text{ A}$		0.720	1.100		
Forward Transconductance	9 _{fs}	V _{DS} = 10 V, I _D = 0.5 A		7.5		S	
Dynamic ^b			-		•		
Input Capacitance	C _{iss}			43		pF	
Output Capacitance	C _{oss}	V_{DS} = 10 V, V_{GS} = 0 V, f = 1 MHz		14			
Reverse Transfer Capacitance	C _{rss}			8			
Total Gata Charge	0	$V_{DS} = 10 \text{ V}, V_{GS} = 8 \text{ V}, I_{D} = 0.6 \text{ A}$		1.3	2	nC	
Total Gate Charge	Qg			0.75	1.2		
Gate-Source Charge	Q _{gs}	$V_{DS} = 10 \text{ V}, \text{ V}_{GS} = 4.5 \text{ V}, \text{ I}_{D} = 0.6 \text{ A}$		0.15			
Gate-Drain Charge	Q _{gd}			0.13			
Gate Resistance	R _g	f = 1 MHz	2.4	12.2	24.4	Ω	
Turn-On Delay Time	t _{d(on)}			11	20		
Rise Time	t _r	V_{DD} = 10 V, R_L = 20 Ω		16	24	- ns	
Turn-Off Delay Time	t _{d(off)}	$\text{I}_\text{D}\cong$ 0.5 A, V_GEN = 4.5 V, R_g = 1 Ω		26	39		
Fall Time	t _f			11	20		
Drain-Source Body Diode Characterist	ics						
Pulse Diode Forward Current ^a	I _{SM}				2	Α	
Body Diode Voltage	V _{SD}	I _S = 0.5 A		0.8	1.2	V	
Body Diode Reverse Recovery Time	t _{rr}			10	15	ns	
Body Diode Reverse Recovery Charge	Q _{rr}	I _F = 0.5 A, dl/dt = 100 A/μs		2	4	nC	
Reverse Recovery Fall Time	t _a	$r_{\rm F} = 0.5$ A, ui/ut = 100 A/µs		5			
Reverse Recovery Rise Time	t _b			5		ns	

Notes:

a. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %.

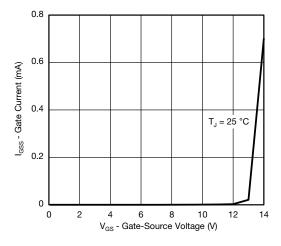
b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

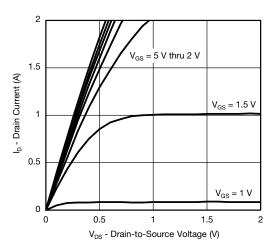
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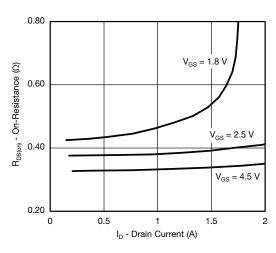
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



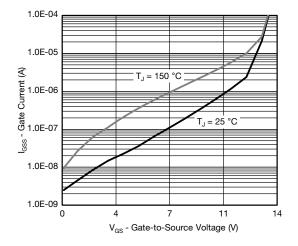
Gate Current vs. Gate-Source Voltage



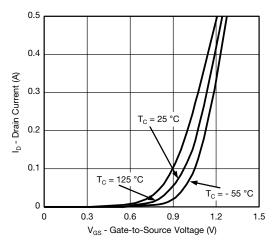
Output Characteristics



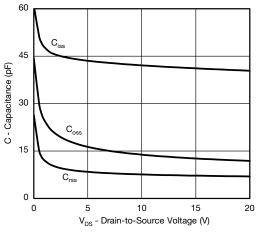
On-Resistance vs. Drain Current



Gate Current vs. Gate-Source Voltage



Transfer Characteristics



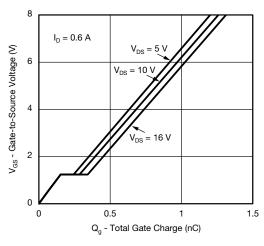
Capacitance

Si1012CR

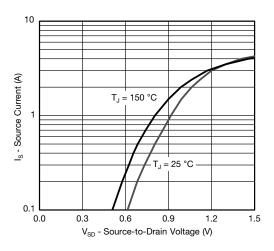
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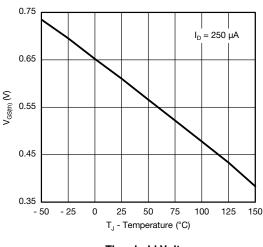
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



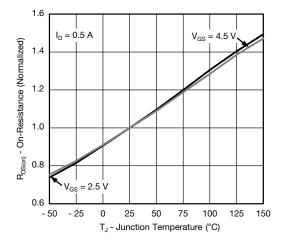
Gate Charge



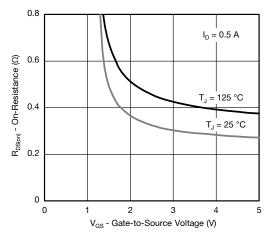
Soure-Drain Diode Forward Voltage



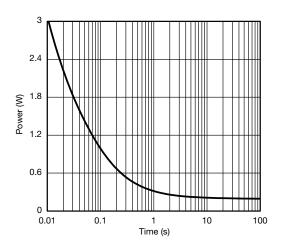
Threshold Voltage



On-Resistance vs. Junction Temperature



On-Resistance vs. Gate-to-Source Voltage



Single Pulse Power, Junction-to-Ambient

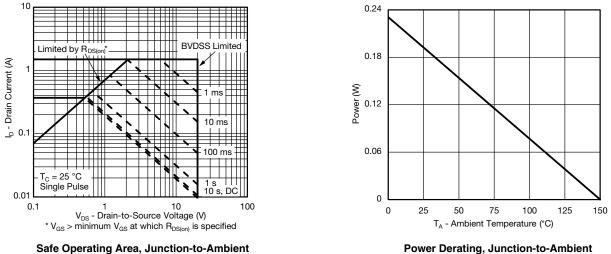
www.vishay.com 4 For technical questions, contact: pmostechsupport@vishay.com

Document Number: 67519 S13-0195-Rev. E, 28-Jan-13

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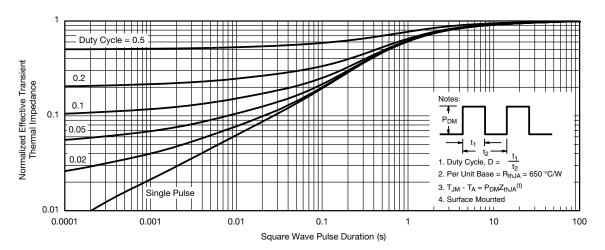


TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Safe Operating Area, Junction-to-Ambient

* The power dissipation P_D is based on $T_{J(max.)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



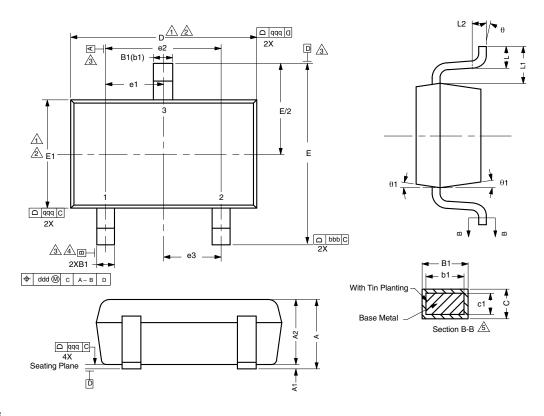
Normalized Thermal Transient Impedance, Junction-to-Ambient

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see www.vishay.com/ppg?67519.



Vishay Siliconix

SC-75A: 3 Leads



DWG: 5868

Notes

Dimensions in millimeters will govern.

- ⚠Dimension D does not include mold flash, protrusions or gate burrs. Mold flash protrusions or gate burrs shall not exceed 0.10 mm per end. Dimension E1 does not include Interlead flash or protrusion. Interlead flash or protrusion shall not exceed 0.10 mm per side.
- 2 Dimensions D and E1 are determined at the outmost extremes of the plastic body exclusive of mold flash, tie bar burrs, gate burrs and interlead flash, but including any mismatch between the top and bottom of the plastic body.
- A Datums A, B and D to be determined 0.10 mm from the lead tip.

A Terminal positions are shown for reference only.

These dimensions apply to the flat section of the lead between 0.08 mm and 0.15 mm from the lead tip.

DIMENSIONS	TOLERANCES
aaa	0.10
bbb	0.10
ссс	0.10
ddd	0.10

DIM.	P	NOTE		
Divi.	MIN.	NOM.	MAX.	NOTE
А	-	-	0.80	
A1	0.00	-	0.10	
A2	0.65	0.70	0.80	
B1	0.19	-	0.24	5
b1	0.17	-	0.21	
с	0.13	-	0.15	5
c1	0.10	-	0.12	5
D	1.48	1.575	1.68	1, 2
E	1.50	1.60	1.70	
E1	0.66	0.76	0.86	1, 2
e1	0.50 BSC			
e2	1.00 BSC			
e3	0.50 BSC			
L	0.15	0.205	0.30	
L1	0.40 ref.			
L2	0.15 BSC			
q	0°	-	8°	
q1	4°	-	10°	

C15-1445-Rev. F, 23-Nov-15

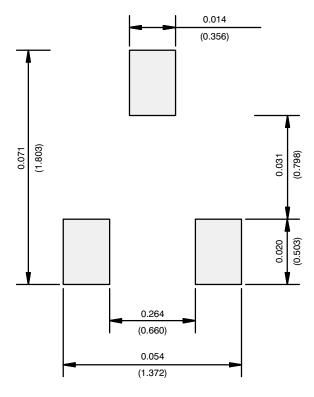
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Application Note 826

Vishay Siliconix

RECOMMENDED MINIMUM PADS FOR SC-75A: 3-Lead



Recommended Minimum Pads Dimensions in Inches/(mm)

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